

PRESS RELEASE

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IPC/APEX Booth #923

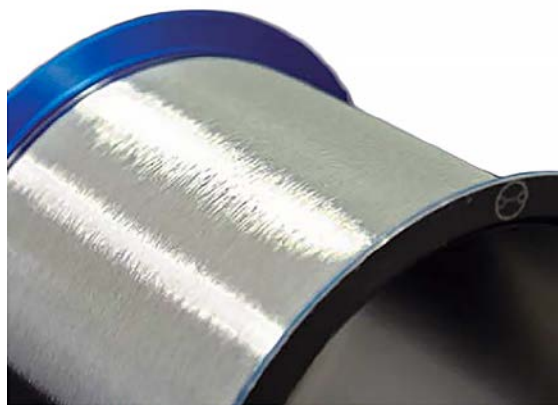
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TopLine Offers Bonding Wire for Universities, Labs, Small-volume Users

Makes Needed Wire Available in Affordable Quantities for Researchers

Irvine, California, USA – TopLine, a leading designer and manufacturer of semiconductor packages and PCB assemblies, has started a new service that makes it much easier for Universities, research facilities, laboratories, and small-volume users to obtain bonding wire manufactured by Tanaka, www.TanakaWire.com. TopLine's One Spool policy allows users to purchase as few as a single spool of bonding-wire. TopLine's policy is welcomed by customers who had been previously forced to purchase large lots of bonding-wire.

“Other manufacturers of bonding wire typically require customers to buy minimum order quantities, which might be 10 to 20 spools,” Martin Hart, TopLine’s President, states. “But TopLine’s M.O.Q. is just One Spool. Our goal is to make it easy for small-volume customers to have quick, hassle-free access to Tanaka’s world -class quality bonding wire, helping Universities, laboratories and R&D projects helps to advance technology, and ultimately the industry that supports all of us,” he added. Examples of Tanaka bonding wire will be on display in the TopLine booth, #923, at the IPC/APEX EXPO 2017 trade show in San Diego, California February 14-16, 2017.



Bonding wire is used in a wide range of applications, mostly involving wiring silicon die inside IC packages or bonding chips directly to PC boards, known as Chip on Board (C.o.B) . The wire is also used to build prototype packages as well as small scale production packages for today's North American market.

TopLine offers a full range of bonding wire in four alloys: Gold, Aluminum, Silver, and Copper, as well as flat gold ribbon used in RF Microwave and certain segments of the solar industry. TopLine offers standard lengths on spools: 50m, 100m, 300m, 500m and 1000m, depending how much the customer needs on the spool. Wire is packaged on two-inch spools as well as half-inch spools for industry standard manual or automated bonding machines.

About TopLine

TopLine Corporation is a leading provider of test vehicle components and packaging solutions for Circuit Assemblies. TopLine manufactures CCGA Column Grid Arrays, solder columns, and a wide range of daisy chain semiconductor packages. TopLine offers a complete range of daisy chain test chips for process development, experimentation, machine evaluation, solder training, and SMT assembly practice.

TopLine products provide hands-on learning for engineers. TopLine is a one-stop source for all dummy components. For more information, contact TopLine Corporation, Tel (800) 776-9888; Email:

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